IN THE CLAIMS:

Please amend Claims 22 and 28 and add Claims 41-52 as follows. Note all the claims currently pending in this application, including those not presently amended, have been reproduced below for the Examiner's convenience.

Claims 1-21. (Canceled)

22. (Currently Amended) A pod for attachment to an outside surface of a grounded electromagnetic-shielded chamber having a door and a grounded flange portion, around the door, on the outside surface and containing a device manufacturing apparatus for processing a substrate, said pod comprising:

walls for containing the substrate; and

a lid for an opening, defined by said walls, through which the substrate is transferred between said pod and the grounded electromagnetic-shielded chamber,

wherein said walls comprise an electromagnetic shield member, said electromagnetic shield member including a flange portion ~~to be in contact with~~ for contacting the grounded flange portion of the grounded electromagnetic-shielded chamber without any intervening elements being present ~~during the attachment of said pod to the outside surface~~.

23. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in front of said pod.

24. (Previously Presented) A pod according to Claim 22, wherein said lid is arranged in a bottom of said pod.

25. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises wire mesh arranged on or within said walls.

26. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises metal coatings arranged on said walls.

27. (Previously Presented) A pod according to Claim 22, wherein said electromagnetic shield member comprises electromagnetic-shield materials arranged in said walls.

28. (Currently Amended) A device manufacturing apparatus for processing a substrate, said apparatus comprising:

an electromagnetic-shielded chamber;

a transfer unit, in said electromagnetic-shielded chamber, to transfer the substrate between said electromagnetic shielded chamber and a pod attached to an outside surface of said electromagnetic-shielded chamber and having an electromagnetic shield member which includes a flange portion to contact the outside surface; and

a processing unit, in said electromagnetic shielded chamber, to process the substrate transferred into said electromagnetic-shielded chamber from the pod by said transfer unit,

wherein said electromagnetic-shielded chamber has a door and a grounded flange portion, around said door, on the outside surface ~~to provide a~~ for providing a grounded connection ~~between said grounded flange portion and~~ with the flange portion of the pod~~-~~ without any intervening elements being present ~~during attachment of the pod to the outside surface~~.

29. (Previously Presented) An apparatus according to claim 28, wherein said transfer unit transfers the substrate between said electromagnetic-shielded chamber and the pod through-said door.

30. (Previously Presented) An apparatus according to 28, wherein said processing unit exposes the substrate to a pattern.

31. (Previously Presented) An apparatus according to Claim 28, wherein a lid of the pod is arranged in front of the pod.

32. (Previously Presented) An apparatus according to Claim 28, wherein a lid of the pod is arranged in a bottom of the pod.

33. (Previously Presented) An apparatus according to Claim 28, wherein walls of the pod comprises the electromagnetic shield member.

Claims 34 through 40 (Canceled)

41. (New) An improved pod for attachment to an outside surface of a grounded electromagnetic-shielded chamber having a door and a flange portion, around the door, on the outside surface and containing a device manufacturing apparatus for processing a substrate, said pod including:

walls for containing the substrate, said walls including a flange portion to contact the flange portion of the grounded electromagnetic-shielded chamber; and

a lid for an opening, defined by said walls, through which the substrate is transferred between said pod and the grounded electromagnetic-shielded chamber,

the improvement comprising:

an electromagnetic shield member, said electromagnetic shield member covering said walls and arranged on said flange portion of said walls.

42. (New) A pod according to Claim 41, wherein said lid is arranged in a front of said pod.

43. (New) A pod according to Claim 41, wherein said lid is arranged in a bottom of said pod.

44. (New) A pod according to Claim 41, wherein said electromagnetic shield member comprises wire mesh arranged on or within said walls.

45. (New) A pod according to Claim 41, wherein said electromagnetic shield member comprises metal coatings arranged on said walls.

46. (New) A pod according to Claim 41, wherein said electromagnetic shield member comprises electromagnetic-shield materials arranged in said walls.

47. (New) An improved device manufacturing apparatus for processing a substrate, said apparatus including:

a grounded electromagnetic-shielded chamber having a door and a flange portion, around said door, on an outside surface of said grounded electromagnetic-shielded chamber;

a transfer unit, arranged in said grounded electromagnetic-shielded chamber, configured to transfer the substrate between said grounded electromagnetic-shielded chamber and a pod, the pod attached to the outside surface and having a flange portion to contact said flange portion of said grounded electromagnetic-shielded chamber; and

a processing unit, arranged in said grounded electromagnetic-shielded chamber, configured to process the substrate transferred into said grounded electromagnetic-shielded chamber from the pod by said transfer unit, improved in that:

said flange portion of said grounded electromagnetic-shielded chamber is grounded.

48. (New) An apparatus according to 47, wherein said transfer unit is configured to transfer the substrate between said grounded electromagnetic-shielded chamber and the pod through said door.

49. (New) An apparatus according to 47, wherein said processing unit is configured to expose the substrate to a pattern.

50. (New) An apparatus according to Claim 47, wherein a lid of the pod is arranged in a front of the pod.

51. (New) An apparatus according to Claim 47, wherein a lid of the pod is arranged in a bottom of the pod.

52. (New) An apparatus according to Claim 47, wherein the pod includes walls for containing the substrate, and a lid for an opening, defined by the walls, through which the substrate is transferred by said transfer unit, the walls including the flange portion of the pod, an electromagnetic shield member covering the walls and arranged on the flange portion of the walls.